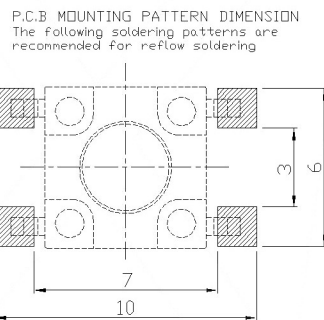
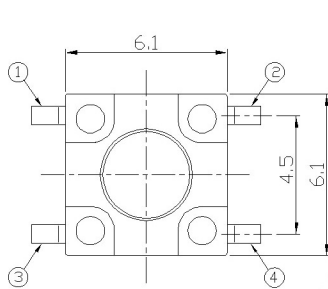
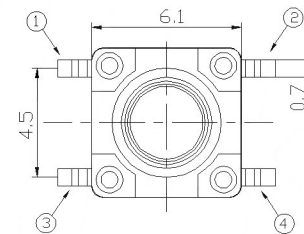


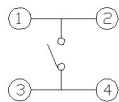
Code-X	H
L	9.5
M	10.0
N	10.5
O	11.0
P	11.5
Q	12
R	12.5
S	13.0
T	13.5
U	14.0
V	15.0
W	15.5
X	16
Y	16.5
Z	17
18	18
19	19



P.C.B MOUNTING PATTERN DIMENSION  
The following soldering patterns are recommended for reflow soldering



CIRCUIT DIAGRAM



Code-X	H
A	4.3
B	4.5
C	5.0
D	5.5
E	6.0
F	6.5
G	7.0
H	7.5
I	8.0
J	8.5
K	9.0

SPECIFICATION

Contact Rating: 50mA,12V DC  
 Contact Resistance: 100mΩ max  
 Insulation Resistance: 100mΩ min.500V DC  
 Dielectric Strength: 250V AC/1 minute  
 Travel: 0.25mm  
 Operating Temp: -25℃ ~+80℃  
 Storage Temp: -30℃ ~+80℃

PAPT NO	TS-FS66T-X-X
Operating Force	A:100gf B:160gf C:260gf
Height	Code-X

ITEM	PAPT NAMF	TER.NO	QTY	MATERIAL	FINISHING	REMARK
⑤	Terminal	4	4	Brass (0.30t)	Plating silvering	
④	Contact	1	1	F.ag/Sus	Natural	
③	Base	1	1	Pa46		
②	Cover	1	1	Pa46		
①	Keystake	1	1	Pa46		

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES
ΔX					units: mm
ΔX					tolerance: X.X ±0.2mm
ΔX					X.XX ±0.1mm
					X.XXX ±0.05mm

DSND	DATE	SCALE: N/A	MODEL TYPE:
DWN	DATE	VIEW:	TACT SWITCH
CHKD	DATE <td>UNIT: mm</td> <td>PART NO.:</td>	UNIT: mm	PART NO.:
APPD	DATE <td>SIZE: A4</td> <td>DWG NO.:</td>	SIZE: A4	DWG NO.:
			TS-FS66T-X-X
		WEIGHT	SHEET
		1.0g	1/1
		REVISION	A0

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